

Product Change Notification - KSRA-05ATCO683

Date:

11 Mar 2019

Product Category:

Linear Regulators; Others

Affected CPNs:

Notification subject:

CCB 3454 and 3454.001 Initial Notice: Qualification of GTBF as a new assembly site for selected products of 0.8um XFAB, 0.8um AMS and 0.6um AMI, 130K and 133K wafer technologies available in 3L and 5L DDPAK packages with MSL 3 classification.

Notification text:
PCN Status:

Initial notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:

Qualification of GTBF as a new assembly site for selected products of 0.8um XFAB, 0.8um AMS and 0.6um AMI, 130K and 133K wafer technologies available in 3L and 5L DDPAK packages.

Pre Change:

Assembled at CARSEM using 84-1 LMISR4 die attach, CEL-9240HF10 molding compound and HCL-12S leadframe material with MSL 1 classification

Post Change:

Assembled at GTBF using CRM-1800 die attach, EME-G600 molding compound and LY80 leadframe material with MSL 3 classification

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Carsem (M) SDN BHD (CARM)	Great Team Backend Foundry (Dong Guan) Ltd. (GTBF)
Wire material	Au wire	Au wire
Die attach material	84-1 LMISR4	CRM-1800
Molding compound material	CEL-9240HF10	EME-G600
Lead frame material	HCL-12S	LY80
MSL Classification	MSL 1	MSL 3

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying GTBF as a new assembly site. CARM assembly site will no longer have manufacturing support for the selected products.



Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

April 2019

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	August 2018					📅	April 2019				
Workweek	31	32	33	34	35	📅	14	15	16	17	18
Initial PCN Issue Date		X									
Qual Report Availability								X			
Final PCN Issue Date								X			

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan

Revision History:

August 10, 2018: Issued initial notification.

March 11, 2019: Re-issued initial notification. Updated the qual plan to change the MSL level classification and added hot temperature 125°C in selected reliability test.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_KSRA-05ATCO683_Qual_Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to [receive Microchip PCNs via email](#) please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to [change your PCN profile, including opt out](#), please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

MCP1790-3002E/EB
MCP1790-3302E/EB
MCP1790-5002E/EB
MCP1790T-3002E/EB
MCP1790T-3302E/EB
MCP1790T-3302E/EBVAO
MCP1790T-5002E/EB
MCP1790T-5002E/EBVAO
MCP1791-3002E/ET
MCP1791-3302E/ET
MCP1791-5002E/ET
MCP1791T-3002E/ET
MCP1791T-3302E/ET
MCP1791T-5002E/ET
MCP1825-0802E/ET
MCP1825-1202E/ET
MCP1825-1802E/ET
MCP1825-2502E/ET
MCP1825-3002E/ET
MCP1825-3302E/ET
MCP1825-5002E/ET
MCP1825-ADJE/ET
MCP1825S-0802E/EB
MCP1825S-1202E/EB
MCP1825S-1802E/EB
MCP1825S-2502E/EB
MCP1825S-3002E/EB
MCP1825S-3302E/EB
MCP1825S-5002E/EB
MCP1825ST-0802E/EB
MCP1825ST-1202E/EB
MCP1825ST-1802E/EB
MCP1825ST-2502E/EB
MCP1825ST-3002E/EB
MCP1825ST-3302E/EB
MCP1825ST-3302E/EBVAO
MCP1825ST-5002E/EB
MCP1825T-0802E/ET
MCP1825T-1202E/ET
MCP1825T-1802E/ET
MCP1825T-2502E/ET
MCP1825T-3002E/ET
MCP1825T-3302E/ET
MCP1825T-5002E/ET
MCP1825T-ADJE/ET
MCP1825T-ADJE/ETVAO

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MCP1826-0802E/ET

MCP1826-1202E/ET

MCP1826-1802E/ET

MCP1826-2502E/ET

MCP1826-3002E/ET

MCP1826-3302E/ET

MCP1826-5002E/ET

MCP1826-ADJE/ET

MCP1826S-0802E/EB

MCP1826S-1202E/EB

MCP1826S-1802E/EB

MCP1826S-2502E/EB

MCP1826S-3002E/EB

MCP1826S-3302E/EB

MCP1826S-5002E/EB

MCP1826ST-0802E/EB

MCP1826ST-1202E/EB

MCP1826ST-1802E/EB

MCP1826ST-2502E/EB

MCP1826ST-3002E/EB

MCP1826ST-3302E/EB

MCP1826ST-5002E/EB

MCP1826T-0802E/ET

MCP1826T-1202E/ET

MCP1826T-1802E/ET

MCP1826T-2502E/ET

MCP1826T-3002E/ET

MCP1826T-3302E/ET

MCP1826T-5002E/ET

MCP1826T-ADJE/ET

MCP1827-0802E/ET

MCP1827-1002E/ET

MCP1827-1202E/ET

MCP1827-1802E/ET

MCP1827-2502E/ET

MCP1827-3002E/ET

MCP1827-3302E/ET

MCP1827-5002E/ET

MCP1827-ADJE/ET

MCP1827S-0802E/EB

MCP1827S-1002E/EB

MCP1827S-1202E/EB

MCP1827S-1802E/EB

MCP1827S-2502E/EB

MCP1827S-3002E/EB

MCP1827S-3302E/EB

MCP1827S-5002E/EB

MCP1827ST-0802E/EB

MCP1827ST-1002E/EB

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MCP1827ST-1202E/EB

MCP1827ST-1802E/EB

MCP1827ST-2502E/EB

MCP1827ST-3002E/EB

MCP1827ST-3302E/EB

MCP1827ST-5002E/EB

MCP1827T-0802E/ET

MCP1827T-1002E/ET

MCP1827T-1202E/ET

MCP1827T-1802E/ET

MCP1827T-2502E/ET

MCP1827T-3002E/ET

MCP1827T-3302E/ET

MCP1827T-5002E/ET

MCP1827T-ADJE/ET

TC1262-2.5VEB

TC1262-2.5VEBTR

TC1262-2.8VEB

TC1262-2.8VEBTR

TC1262-3.0VEB

TC1262-3.0VEBTR

TC1262-3.3VEB

TC1262-3.3VEBTR

TC1262-5.0VEB

TC1262-5.0VEBTR

TC1263-2.5VET

TC1263-2.5VETTR

TC1263-2.8VET

TC1263-2.8VETTR

TC1263-3.0VET

TC1263-3.0VETTR

TC1263-3.3VET

TC1263-3.3VETTR

TC1263-5.0VET

TC1263-5.0VETTR

TC1264-1.8VEB

TC1264-1.8VEBTR

TC1264-2.5VEB

TC1264-2.5VEBTR

TC1264-3.0VEB

TC1264-3.0VEBTR

TC1264-3.3VEB

TC1264-3.3VEBTR

TC1265-1.8VET

TC1265-1.8VETTR

TC1265-2.5VET

TC1265-2.5VETTR

TC1265-3.0VET

TC1265-3.0VETTR

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TC1265-3.3VE1

TC1265-3.3VETTR